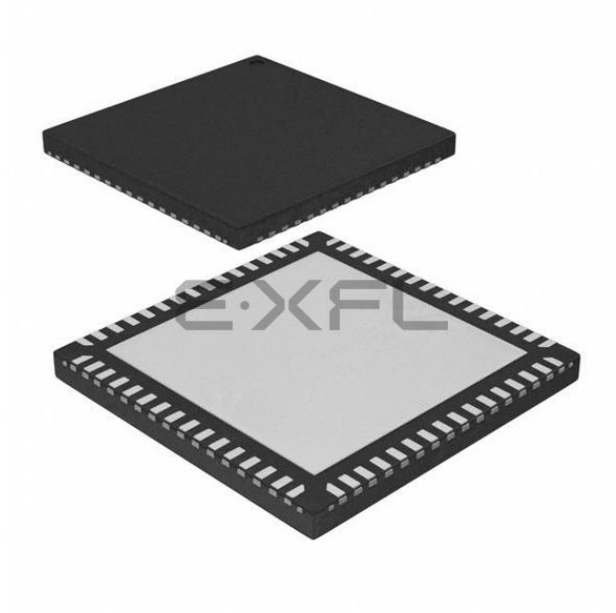

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	AVR
Core Size	32-Bit Single-Core
Speed	66MHz
Connectivity	CANbus, Ethernet, I²C, IrDA, LINbus, SPI, UART/USART, USB
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	45
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 11x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-QFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at32uc3c2256c-z2zt

Table 3-1. GPIO Controller Function Multiplexing

TQFP / QFN 64	TQFP 100	LQFP 144	PIN	GPIO	Supply	Pin Type (1)	GPIO function					
							A	B	C	D	E	F
33	51	73	PC02	66	VDDIO2	x1	TWIMS0 - TWD	SPI0 - NPCS[3]	USART2 - RXD	TC1 - CLK1	MACB - MDC	
34	52	74	PC03	67	VDDIO2	x1	TWIMS0 - TWCK	EIC - EXTINT[1]	USART2 - TXD	TC1 - B1	MACB - MDIO	
37	55	77	PC04	68	VDDIO2	x1	TWIMS1 - TWD	EIC - EXTINT[3]	USART2 - TXD	TC0 - B1		
38	56	78	PC05	69	VDDIO2	x1	TWIMS1 - TWCK	EIC - EXTINT[4]	USART2 - RXD	TC0 - A2		
	57	79	PC06	70	VDDIO2	x1	PEVC - PAD_EVT [15]	USART2 - CLK	USART2 - CTS	TC0 - CLK2	TWIMS2 - TWD	TWIMS0 - TWALM
	58	80	PC07	71	VDDIO2	x1	PEVC - PAD_EVT [2]	EBI - NCS[3]	USART2 - RTS	TC0 - B2	TWIMS2 - TWCK	TWIMS1 - TWALM
		81	PC08	72	VDDIO2	x1/x2	PEVC - PAD_EVT [13]	SPI1 - NPCS[1]	EBI - NCS[0]		USART4 - TXD	
		82	PC09	73	VDDIO2	x1/x2	PEVC - PAD_EVT [14]	SPI1 - NPCS[2]	EBI - ADDR[23]		USART4 - RXD	
		83	PC10	74	VDDIO2	x1/x2	PEVC - PAD_EVT [15]	SPI1 - NPCS[3]	EBI - ADDR[22]			
	59	84	PC11	75	VDDIO2	x1/x2	PWM - PWMH[3]	CANIF - RXLINE[1]	EBI - ADDR[21]	TC0 - CLK0		
	60	85	PC12	76	VDDIO2	x1/x2	PWM - PWML[3]	CANIF - TXLINE[1]	EBI - ADDR[20]	USART2 - CLK		
	61	86	PC13	77	VDDIO2	x1/x2	PWM - PWMH[2]	EIC - EXTINT[7]		USART0 - RTS		
	62	87	PC14	78	VDDIO2	x1/x2	PWM - PWML[2]	USART0 - CLK	EBI - SDCKE	USART0 - CTS		
39	63	88	PC15	79	VDDIO2	x1/x2	PWM - PWMH[1]	SPI0 - NPCS[0]	EBI - SDWE	USART0 - RXD	CANIF - RXLINE[1]	
40	64	89	PC16	80	VDDIO2	x1/x2	PWM - PWML[1]	SPI0 - NPCS[1]	EBI - CAS	USART0 - TXD	CANIF - TXLINE[1]	
41	65	90	PC17	81	VDDIO2	x1/x2	PWM - PWMH[0]	SPI0 - NPCS[2]	EBI - RAS	IISC - ISDO		USART3 - TXD
42	66	91	PC18	82	VDDIO2	x1/x2	PWM - PWML[0]	EIC - EXTINT[5]	EBI - SDA10	IISC - ISDI		USART3 - RXD
43	67	92	PC19	83	VDDIO3	x1/x2	PWM - PWML[2]	SCIF - GCLK[0]	EBI - DATA[0]	IISC - IMCK		USART3 - CTS
44	68	93	PC20	84	VDDIO3	x1/x2	PWM - PWMH[2]	SCIF - GCLK[1]	EBI - DATA[1]	IISC - ISCK		USART3 - RTS
45	69	94	PC21	85	VDDIO3	x1/x2	PWM - EXT_ FAULTS[0]	CANIF - RXLINE[0]	EBI - DATA[2]	IISC - IWS		
46	70	95	PC22	86	VDDIO3	x1/x2	PWM - EXT_ FAULTS[1]	CANIF - TXLINE[0]	EBI - DATA[3]		USART3 - CLK	
	71	96	PC23	87	VDDIO3	x1/x2	QDEC1 - QEPB	CANIF - RXLINE[1]	EBI - DATA[4]	PEVC - PAD_EVT [3]		

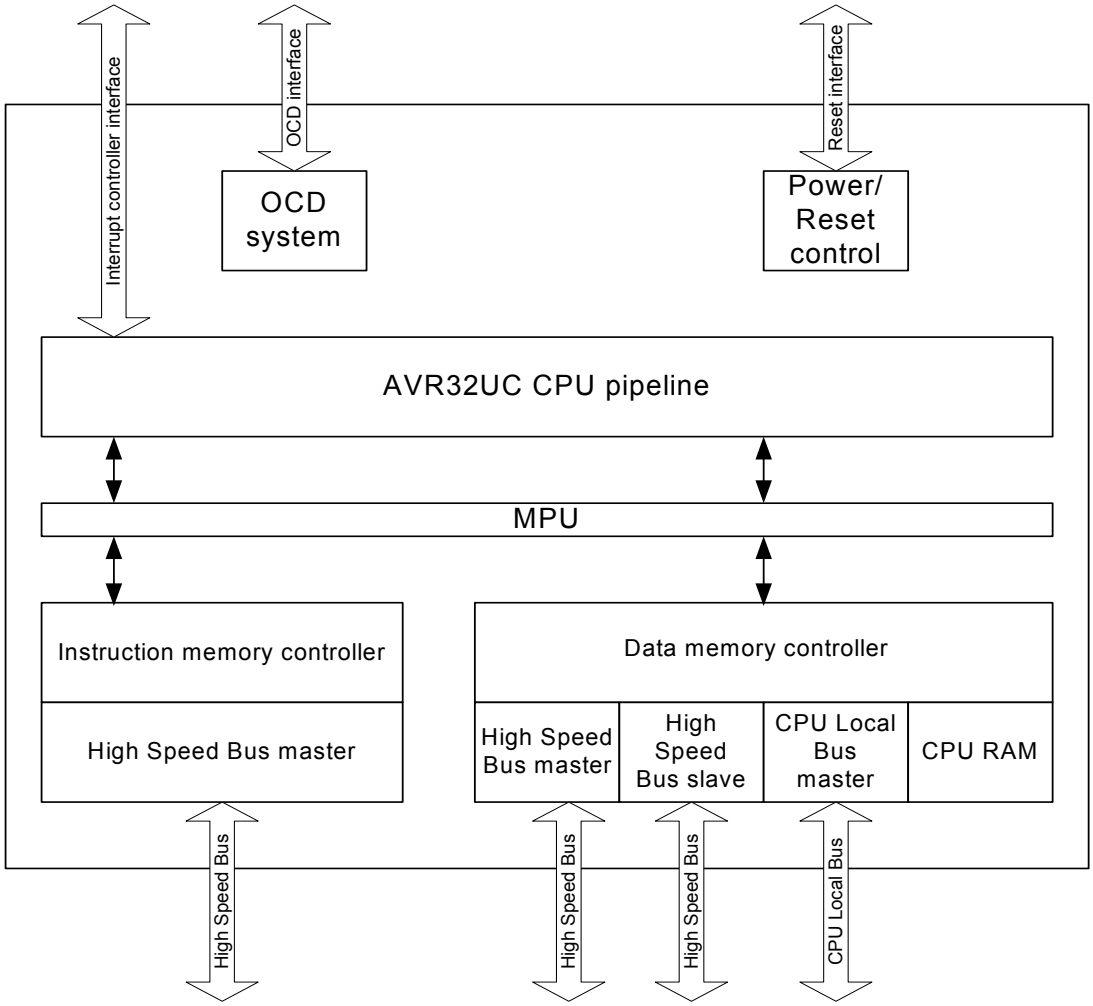
Table 3-1. GPIO Controller Function Multiplexing

TQFP / QFN 64	TQFP 100	LQFP 144	PIN	GPIO	Supply	Pin Type (1)	GPIO function					
							A	B	C	D	E	F
	72	97	PC24	88	VDDIO3	x1/x2	QDEC1 - QEPA	CANIF - TXLINE[1]	EBI - DATA[5]	PEVC - PAD_EVT [4]		
		98	PC25	89	VDDIO3	x1/x2		TC1 - CLK2	EBI - DATA[6]	SCIF - GCLK[0]	USART4 - TXD	
		99	PC26	90	VDDIO3	x1/x2	QDEC1 - QEPI	TC1 - B2	EBI - DATA[7]	SCIF - GCLK[1]	USART4 - RXD	
		100	PC27	91	VDDIO3	x1/x2		TC1 - A2	EBI - DATA[8]	EIC - EXTINT[0]	USART4 - CTS	
		101	PC28	92	VDDIO3	x1/x2	SPI1 - NPCS[3]	TC1 - CLK1	EBI - DATA[9]		USART4 - RTS	
		102	PC29	93	VDDIO3	x1/x2	SPI0 - NPCS[1]	TC1 - B1	EBI - DATA[10]			
		105	PC30	94	VDDIO3	x1/x2	SPI0 - NPCS[2]	TC1 - A1	EBI - DATA[11]			
	73	106	PC31	95	VDDIO3	x1/x2	SPI0 - NPCS[3]	TC1 - B0	EBI - DATA[12]	PEVC - PAD_EVT [5]	USART4 - CLK	
47	74	107	PD00	96	VDDIO3	x1/x2	SPI0 - MOSI	TC1 - CLK0	EBI - DATA[13]	QDEC0 - QEPI	USART0 - TXD	
48	75	108	PD01	97	VDDIO3	x1/x2	SPI0 - MISO	TC1 - A0	EBI - DATA[14]	TC0 - CLK1	USART0 - RXD	
49	76	109	PD02	98	VDDIO3	x2/x4	SPI0 - SCK	TC0 - CLK2	EBI - DATA[15]	QDEC0 - QEPA		
50	77	110	PD03	99	VDDIO3	x1/x2	SPI0 - NPCS[0]	TC0 - B2	EBI - ADDR[0]	QDEC0 - QEPB		
		111	PD04	100	VDDIO3	x1/x2	SPI0 - MOSI		EBI - ADDR[1]			
		112	PD05	101	VDDIO3	x1/x2	SPI0 - MISO		EBI - ADDR[2]			
		113	PD06	102	VDDIO3	x2/x4	SPI0 - SCK		EBI - ADDR[3]			
	78	114	PD07	103	VDDIO3	x1/x2	USART1 - DTR	EIC - EXTINT[5]	EBI - ADDR[4]	QDEC0 - QEPI	USART4 - TXD	
	79	115	PD08	104	VDDIO3	x1/x2	USART1 - DSR	EIC - EXTINT[6]	EBI - ADDR[5]	TC1 - CLK2	USART4 - RXD	
	80	116	PD09	105	VDDIO3	x1/x2	USART1 - DCD	CANIF - RXLINE[0]	EBI - ADDR[6]	QDEC0 - QEPA	USART4 - CTS	
	81	117	PD10	106	VDDIO3	x1/x2	USART1 - RI	CANIF - TXLINE[0]	EBI - ADDR[7]	QDEC0 - QEPB	USART4 - RTS	
53	84	120	PD11	107	VDDIO3	x1/x2	USART1 - TXD	USBC - ID	EBI - ADDR[8]	PEVC - PAD_EVT [6]	MACB - TXD[0]	
54	85	121	PD12	108	VDDIO3	x1/x2	USART1 - RXD	USBC - VBOF	EBI - ADDR[9]	PEVC - PAD_EVT [7]	MACB - TXD[1]	
55	86	122	PD13	109	VDDIO3	x2/x4	USART1 - CTS	USART1 - CLK	EBI - SDCK	PEVC - PAD_EVT [8]	MACB - RXD[0]	
56	87	123	PD14	110	VDDIO3	x1/x2	USART1 - RTS	EIC - EXTINT[7]	EBI - ADDR[10]	PEVC - PAD_EVT [9]	MACB - RXD[1]	

Table 3-7. Signal Description List

Signal Name	Function	Type	Active Level	Comments
VDDIN_5	1.8V Voltage Regulator Input	Power Input		Power Supply: 4.5V to 5.5V or 3.0V to 3.6 V
VDDIN_33	USB I/O power supply	Power Output/ Input		Capacitor Connection for the 3.3V voltage regulator or power supply: 3.0V to 3.6 V
VDDCORE	1.8V Voltage Regulator Output	Power output		Capacitor Connection for the 1.8V voltage regulator
GNDIO1 GNDIO2 GNDIO3	I/O Ground	Ground		
GNDANA	Analog Ground	Ground		
GNDCORE	Ground of the core	Ground		
GNDPLL	Ground of the PLLs	Ground		
Analog Comparator Interface - ACIFA0/1				
AC0AN1/AC0AN0	Negative inputs for comparator AC0A	Analog		
AC0AP1/AC0AP0	Positive inputs for comparator AC0A	Analog		
AC0BN1/AC0BN0	Negative inputs for comparator AC0B	Analog		
AC0BP1/AC0BP0	Positive inputs for comparator AC0B	Analog		
AC1AN1/AC1AN0	Negative inputs for comparator AC1A	Analog		
AC1AP1/AC1AP0	Positive inputs for comparator AC1A	Analog		
AC1BN1/AC1BN0	Negative inputs for comparator AC1B	Analog		
AC1BP1/AC1BP0	Positive inputs for comparator AC1B	Analog		
ACAOUT/ACBOUT	analog comparator outputs	output		
ADC Interface - ADCIFA				
ADCIN[15:0]	ADC input pins	Analog		
ADCREF0	Analog positive reference 0 voltage input	Analog		
ADCREF1	Analog positive reference 1 voltage input	Analog		
ADCVREFP	Analog positive reference connected to external capacitor	Analog		

Figure 4-1. Overview of the AVR32UC CPU



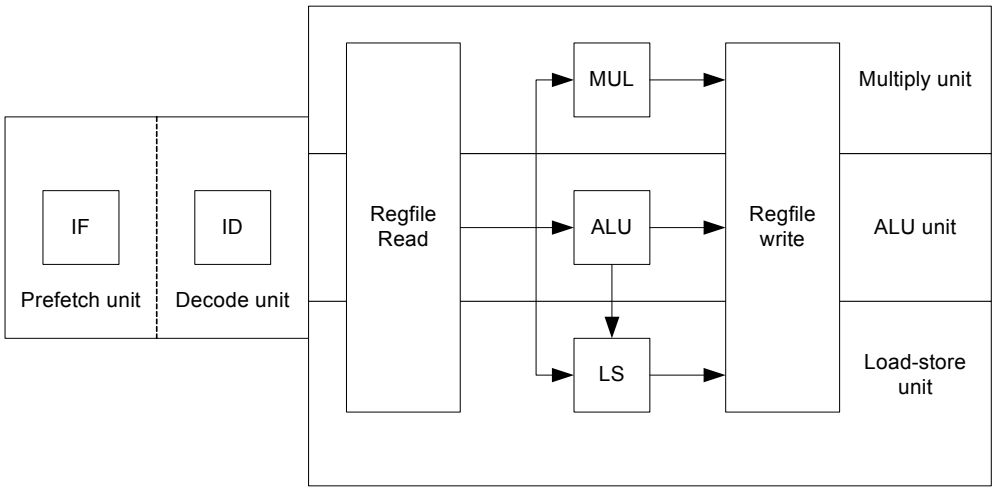
4.3.1 Pipeline Overview

AVR32UC has three pipeline stages, Instruction Fetch (IF), Instruction Decode (ID), and Instruction Execute (EX). The EX stage is split into three parallel subsections, one arithmetic/logic (ALU) section, one multiply (MUL) section, and one load/store (LS) section.

Instructions are issued and complete in order. Certain operations require several clock cycles to complete, and in this case, the instruction resides in the ID and EX stages for the required number of clock cycles. Since there is only three pipeline stages, no internal data forwarding is required, and no data dependencies can arise in the pipeline.

Figure 4-2 on page 28 shows an overview of the AVR32UC pipeline stages.

Figure 4-2. The AVR32UC Pipeline



4.3.2 AVR32A Microarchitecture Compliance

AVR32UC implements an AVR32A microarchitecture. The AVR32A microarchitecture is targeted at cost-sensitive, lower-end applications like smaller microcontrollers. This microarchitecture does not provide dedicated hardware registers for shadowing of register file registers in interrupt contexts. Additionally, it does not provide hardware registers for the return address registers and return status registers. Instead, all this information is stored on the system stack. This saves chip area at the expense of slower interrupt handling.

4.3.2.1 Interrupt Handling

Upon interrupt initiation, registers R8-R12 are automatically pushed to the system stack. These registers are pushed regardless of the priority level of the pending interrupt. The return address and status register are also automatically pushed to stack. The interrupt handler can therefore use R8-R12 freely. Upon interrupt completion, the old R8-R12 registers and status register are restored, and execution continues at the return address stored popped from stack.

The stack is also used to store the status register and return address for exceptions and *scall*. Executing the *rete* or *rets* instruction at the completion of an exception or system call will pop this status register and continue execution at the popped return address.

4.3.2.2 Java Support

AVR32UC does not provide Java hardware acceleration.

4.3.2.3 Floating Point Support

A fused multiply-accumulate Floating Point Unit (FPU), performaing a multiply and accumulate as a single operation with no intermediate rounding, therby increasing precision is provided. The floating point hardware conforms to the requirements of the C standard, which is based on the IEEE 754 floating point standard.

4.3.2.4 Memory Protection

The MPU allows the user to check all memory accesses for privilege violations. If an access is attempted to an illegal memory address, the access is aborted and an exception is taken. The MPU in AVR32UC is specified in the AVR32UC Technical Reference manual.

relative to EVBA. The autovector offset has 14 address bits, giving an offset of maximum 16384 bytes. The target address of the event handler is calculated as (EVBA | event_handler_offset), not (EVBA + event_handler_offset), so EVBA and exception code segments must be set up appropriately. The same mechanisms are used to service all different types of events, including interrupt requests, yielding a uniform event handling scheme.

An interrupt controller does the priority handling of the interrupts and provides the autovector offset to the CPU.

4.5.1 System Stack Issues

Event handling in AVR32UC uses the system stack pointed to by the system stack pointer, SP_SYS, for pushing and popping R8-R12, LR, status register, and return address. Since event code may be timing-critical, SP_SYS should point to memory addresses in the IRAM section, since the timing of accesses to this memory section is both fast and deterministic.

The user must also make sure that the system stack is large enough so that any event is able to push the required registers to stack. If the system stack is full, and an event occurs, the system will enter an UNDEFINED state.

4.5.2 Exceptions and Interrupt Requests

When an event other than *scall* or debug request is received by the core, the following actions are performed atomically:

1. The pending event will not be accepted if it is masked. The I3M, I2M, I1M, I0M, EM, and GM bits in the Status Register are used to mask different events. Not all events can be masked. A few critical events (NMI, Unrecoverable Exception, TLB Multiple Hit, and Bus Error) can not be masked. When an event is accepted, hardware automatically sets the mask bits corresponding to all sources with equal or lower priority. This inhibits acceptance of other events of the same or lower priority, except for the critical events listed above. Software may choose to clear some or all of these bits after saving the necessary state if other priority schemes are desired. It is the event source's responsability to ensure that their events are left pending until accepted by the CPU.
2. When a request is accepted, the Status Register and Program Counter of the current context is stored to the system stack. If the event is an INT0, INT1, INT2, or INT3, registers R8-R12 and LR are also automatically stored to stack. Storing the Status Register ensures that the core is returned to the previous execution mode when the current event handling is completed. When exceptions occur, both the EM and GM bits are set, and the application may manually enable nested exceptions if desired by clearing the appropriate bit. Each exception handler has a dedicated handler address, and this address uniquely identifies the exception source.
3. The Mode bits are set to reflect the priority of the accepted event, and the correct register file bank is selected. The address of the event handler, as shown in Table 4-4 on page 38, is loaded into the Program Counter.

The execution of the event handler routine then continues from the effective address calculated.

The *rete* instruction signals the end of the event. When encountered, the Return Status Register and Return Address Register are popped from the system stack and restored to the Status Register and Program Counter. If the *rete* instruction returns from INT0, INT1, INT2, or INT3, registers R8-R12 and LR are also popped from the system stack. The restored Status Register contains information allowing the core to resume operation in the previous execution mode. This concludes the event handling.

5.2 Physical Memory Map

The system bus is implemented as a bus matrix. All system bus addresses are fixed, and they are never remapped in any way, not even in boot. Note that AVR32UC CPU uses unsegmented translation, as described in the AVR32 Architecture Manual. The 32-bit physical address space is mapped as follows:

Table 5-1. AT32UC3C Physical Memory Map

Device	Start Address	AT32UC3 Derivatives			
		C0512C	C1512C C2512C	C1256C C2256C	C2128C
Embedded SRAM	0x0000_0000	64 KB	64 KB	64 KB	32 KB
Embedded Flash	0x8000_0000	512 KB	512 KB	256 KB	128 KB
SAU	0x9000_0000	1 KB	1 KB	1 KB	1 KB
HSB SRAM	0xA000_0000	4 KB	4 KB	4 KB	4 KB
EBI SRAM CS0	0xC000_0000	16 MB	-	-	-
EBI SRAM CS2	0xC800_0000	16 MB	-	-	-
EBI SRAM CS3	0xCC00_0000	16 MB	-	-	-
EBI SRAM CS1 /SDRAM CS0	0xD000_0000	128 MB	-	-	-
HSB-PB Bridge C	0xFFFD_0000	64 KB	64 KB	64 KB	64 KB
HSB-PB Bridge B	0xFFFE_0000	64 KB	64 KB	64 KB	64 KB
HSB-PB Bridge A	0xFFFF_0000	64 KB	64 KB	64 KB	64 KB

Table 5-2. Flash Memory Parameters

Part Number	Flash Size (FLASH_PW)	Number of pages (FLASH_P)	Page size (FLASH_W)
AT32UC3C0512C AT32UC3C1512C AT32UC3C2512C	512 Kbytes	1024	128 words
AT32UC3C1256C AT32UC3C2256C	256 Kbytes	512	128 words
AT32UC3C2128C	128 Kbytes	256	128 words

5.3 Peripheral Address Map

Table 5-3. Peripheral Address Mapping

Address	Peripheral Name	
0xFFFD0000	PDCA	Peripheral DMA Controller - PDCA

Table 5-4. Local bus mapped GPIO registers

Port	Register	Mode	Local Bus Address	Access
B	Output Driver Enable Register (ODER)	WRITE	0x40000140	Write-only
		SET	0x40000144	Write-only
		CLEAR	0x40000148	Write-only
		TOGGLE	0x4000014C	Write-only
	Output Value Register (OVR)	WRITE	0x40000150	Write-only
		SET	0x40000154	Write-only
		CLEAR	0x40000158	Write-only
		TOGGLE	0x4000015C	Write-only
	Pin Value Register (PVR)	-	0x40000160	Read-only
C	Output Driver Enable Register (ODER)	WRITE	0x40000240	Write-only
		SET	0x40000244	Write-only
		CLEAR	0x40000248	Write-only
		TOGGLE	0x4000024C	Write-only
	Output Value Register (OVR)	WRITE	0x40000250	Write-only
		SET	0x40000254	Write-only
		CLEAR	0x40000258	Write-only
		TOGGLE	0x4000025C	Write-only
	Pin Value Register (PVR)	-	0x40000260	Read-only
D	Output Driver Enable Register (ODER)	WRITE	0x40000340	Write-only
		SET	0x40000344	Write-only
		CLEAR	0x40000348	Write-only
		TOGGLE	0x4000034C	Write-only
	Output Value Register (OVR)	WRITE	0x40000350	Write-only
		SET	0x40000354	Write-only
		CLEAR	0x40000358	Write-only
		TOGGLE	0x4000035C	Write-only
	Pin Value Register (PVR)	-	0x40000360	Read-only

7. Electrical Characteristics

7.1 Absolute Maximum Ratings*

Operating temperature	-40°C to +125°C
Storage temperature	-60°C to +150°C
Voltage on any pin except DM/DP/VBUS with respect to ground	-0.3V to V_{VDD}[1]+0.3V
Voltage on DM/DP with respect to ground	-0.3V to +3.6V
Voltage on VBUS with respect to ground	-0.3V to +5.5V
Maximum operating voltage (VDDIN_5)	5.5V
Maximum operating voltage (VDDIO1, VDDIO2, VDDIO3, VDDANA)	5.5V
Maximum operating voltage (VDDIN_33)	3.6V
Total DC output current on all I/O pins- VDDIO1	40 mA
Total DC output current on all I/O pins- VDDIO2	40 mA
Total DC output current on all I/O pins- VDDIO3	40 mA
Total DC output current on all I/O pins- VDDANA	40 mA

*NOTICE: Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Notes: 1. V_{VDD} corresponds to either V_{VDDIO1}, V_{VDDIO2}, V_{VDDIO3}, or V_{VDDANA}, depending on the supply for the pin. Refer to Section 3-1 on page 11 for details.

7.2 Supply Characteristics

The following characteristics are applicable to the operating temperature range: T_A = -40°C to 125°C, unless otherwise specified and are valid for a junction temperature up to T_J = 145°C. Please refer to Section 6. ”Supply and Startup Considerations” on page 45.

Table 7-1. Supply Characteristics

Symbol	Parameter	Condition	Voltage		
			Min	Max	Unit
V_{VDDIN_5}	DC supply internal regulators	3V range	3.0	3.6	V
		5V range	4.5	5.5	
V_{VDDIN_33}	DC supply USB I/O	only in 3V range	3.0	3.6	V
V_{VDDANA}	DC supply peripheral I/O and analog part	3V range	3.0	3.6	V
		5V range	4.5	5.5	
V_{VDDIO1} V_{VDDIO2} V_{VDDIO2}	DC supply peripheral I/O	3V range	3.0	3.6	V
		5V range	4.5	5.5	

Table 7-2. Supply Rise Rates and Order

Symbol	Parameter	Rise Rate		
		Min	Max	Comment
V_{VDDIN_5}	DC supply internal 3.3V regulator	0.01 V/ms	1.25 V/us	
V_{VDDIN_33}	DC supply internal 1.8V regulator	0.01 V/ms	1.25 V/us	
V_{VDDIO1} V_{VDDIO2} V_{VDDIO3}	DC supply peripheral I/O	0.01 V/ms	1.25 V/us	Rise after or at the same time as VDDIN_5, VDDIN_33
V_{VDDANA}	DC supply peripheral I/O and analog part	0.01 V/ms	1.25 V/us	Rise after or at the same time as VDDIN_5, VDDIN_33

7.3 Maximum Clock Frequencies

These parameters are given in the following conditions:

- $V_{VDDCORE}$ > 1.85V
- Temperature = -40°C to 125°C

Table 7-3. Clock Frequencies

Symbol	Parameter	Conditions	Min	Max	Units
f_{CPU}	CPU clock frequency			50	MHz
f_{PBA}	PBA clock frequency			50	MHz
f_{PBB}	PBB clock frequency			50	MHz
f_{PBC}	PBC clock frequency			50	MHz
f_{GCLK0}	GCLK0 clock frequency	Generic clock for USBC		50(1)	MHz
f_{GCLK1}	GCLK1 clock frequency	Generic clock for CANIF		66(1)	MHz
f_{GCLK2}	GCLK2 clock frequency	Generic clock for AST		80(1)	MHz
f_{GCLK4}	GCLK4 clock frequency	Generic clock for PWM		120(1)	MHz
f_{GCLK11}	GCLK11 clock frequency	Generic clock for IISC		50(1)	MHz

Note: 1. These values are based on simulation and characterization of other AVR microcontrollers manufactured in the same process technology. These values are not covered by test limits in production.

7.4 Power Consumption

The values in Table 7-4 are measured values of power consumption under the following conditions, except where noted:

- Operating conditions core supply (Figure 7-1)
  - V_{VDDIN_5} = V_{VDDIN_33} = 3.3V
  - $V_{VDDCORE}$ = 1.85V, supplied by the internal regulator
  - V_{VDDIO1} = V_{VDDIO2} = V_{VDDIO3} = 3.3V
  - V_{VDDANA} = 3.3V

  - Internal 3.3V regulator is off
- T_A = 25°C
- I/Os are configured as inputs, with internal pull-up enabled.
- Oscillators
  - OSC0/1 (crystal oscillator) stopped
  - OSC32K (32KHz crystal oscillator) stopped
  - PLL0 running
  - PLL1 stopped
- Clocks
  - External clock on XIN0 as main clock source **(**10MHz**)**
  - CPU, HSB, and PBB clocks undivided
  - PBA, PBC clock divided by 4
  - All peripheral clocks running

Table 7-4. Power Consumption for Different Operating Modes

Mode	Conditions	Measured on	Consumption Typ	Unit
Active[1]	CPU running a recursive Fibonacci algorithm	Amp	512	µA/MHz
Idle[1]			258	
Frozen[1]			106	
Standby[1]			48	
Stop			73	µA
DeepStop			43	
Static	OSC32K and AST running		32	
	AST and OSC32K stopped		31	

Note: 1. These numbers are valid for the measured condition only and must not be extrapolated to other frequencies.

7.5 I/O Pin Characteristics

Table 7-6. Normal I/O Pin Characteristics[1]

Symbol	Parameter	Condition		Min	Typ	Max	Units
R_{PULLUP}	Pull-up resistance	V_{VDD} = 3V		5		26	kOhm
		V_{VDD} = 5V		5		16	kOhm
$R_{PULLDOWN}$	Pull-down resistance			2		16	kOhm
V_{IL}	Input low-level voltage	V_{VDD} = 3V				$0.3*V_{VDDIO}$	V
		V_{VDD} = 4.5V				$0.3*V_{VDDIO}$	
V_{IH}	Input high-level voltage	V_{VDD} = 3.6V		$0.7*V_{VDDIO}$			V
		V_{VDD} = 5.5V		$0.7*V_{VDDIO}$			
V_{OL}	Output low-level voltage	I_{OL} = -3.5mA, pin drive x1[2]				0.5	V
		I_{OL} = -7mA, pin drive x2[2]					
		I_{OL} = -14mA, pin drive x4[2]					
V_{OH}	Output high-level voltage	I_{OH} = 3.5mA, pin drive x1[2]		V_{VDD} - 0.8			V
		I_{OH} = 7mA, pin drive x2[2]					
		I_{OH} = 14mA, pin drive x4[2]					
f_{MAX}	Output frequency[3]	V_{VDD} = 3.0V	load = 10pF, pin drive x1[2]			30	MHz
			load = 10pF, pin drive x2[2]			50	
			load = 10pF, pin drive x4[2]			60	
			load = 30pF, pin drive x1[2]			15	
			load = 30pF, pin drive x2[2]			25	
			load = 30pF, pin drive x4[2]			40	
		V_{VDD} =4.5V	load = 10pF, pin drive x1[2]			45	
			load = 10pF, pin drive x2[2]			65	
			load = 10pF, pin drive x4[2]			85	
			load = 30pF, pin drive x1[2]			20	
			load = 30pF, pin drive x2[2]			40	
			load = 30pF, pin drive x4[2]			60	

Figure 7-19. SDRAMC Signals relative to SDCK.

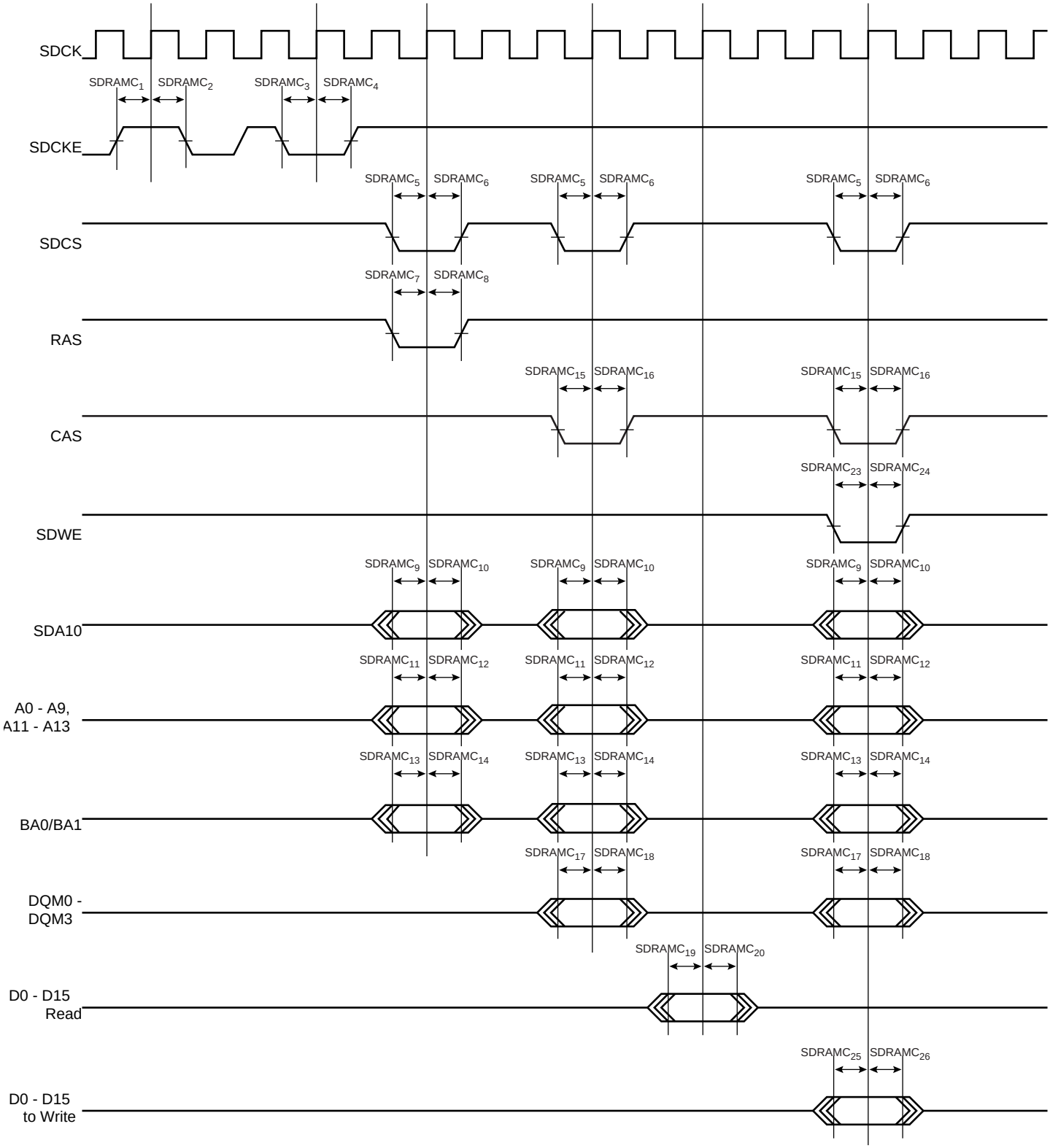
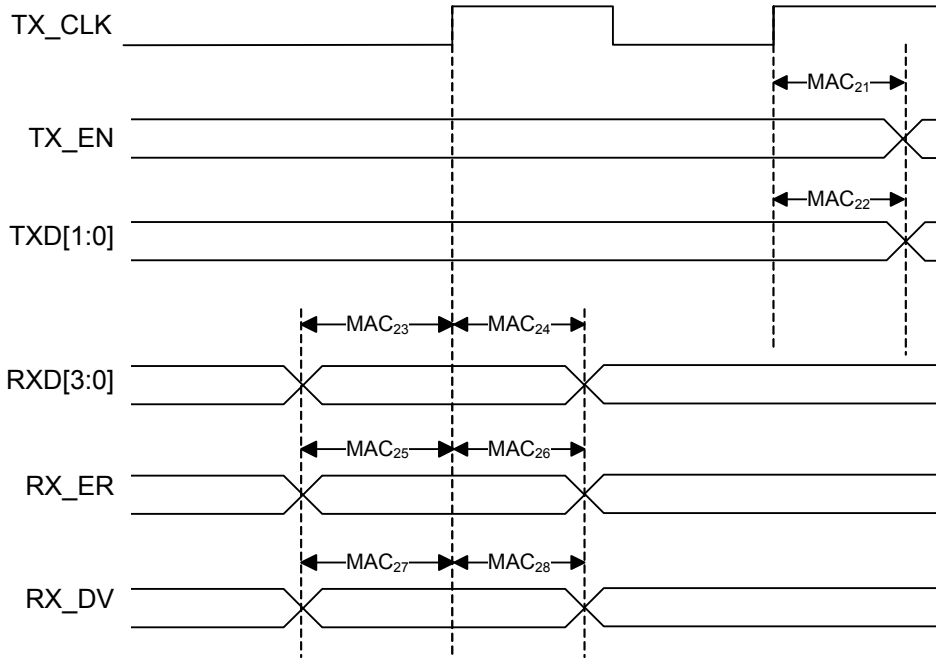


Table 7-61. Ethernet MAC RMII Specific Signals[1]

Symbol	Parameter	Conditions	Min.	Max.	Unit
MAC_{21}	TX_EN toggling from TX_CLK rising	V_{VDD} = 3.0V, drive strength of the pads set to the highest, external capacitor = 10pF on MACB pins	12.5	13.4	ns
MAC_{22}	TXD toggling from TX_CLK rising		12.5	13.4	ns
MAC_{23}	Setup for RXD from TX_CLK		4.7		ns
MAC_{24}	Hold for RXD from TX_CLK		0		ns
MAC_{25}	Setup for RX_ER from TX_CLK		3.6		ns
MAC_{26}	Hold for RX_ER from TX_CLK		0		ns
MAC_{27}	Setup for RX_DV from TX_CLK		4.6		ns
MAC_{28}	Hold for RX_DV from TX_CLK		0		ns

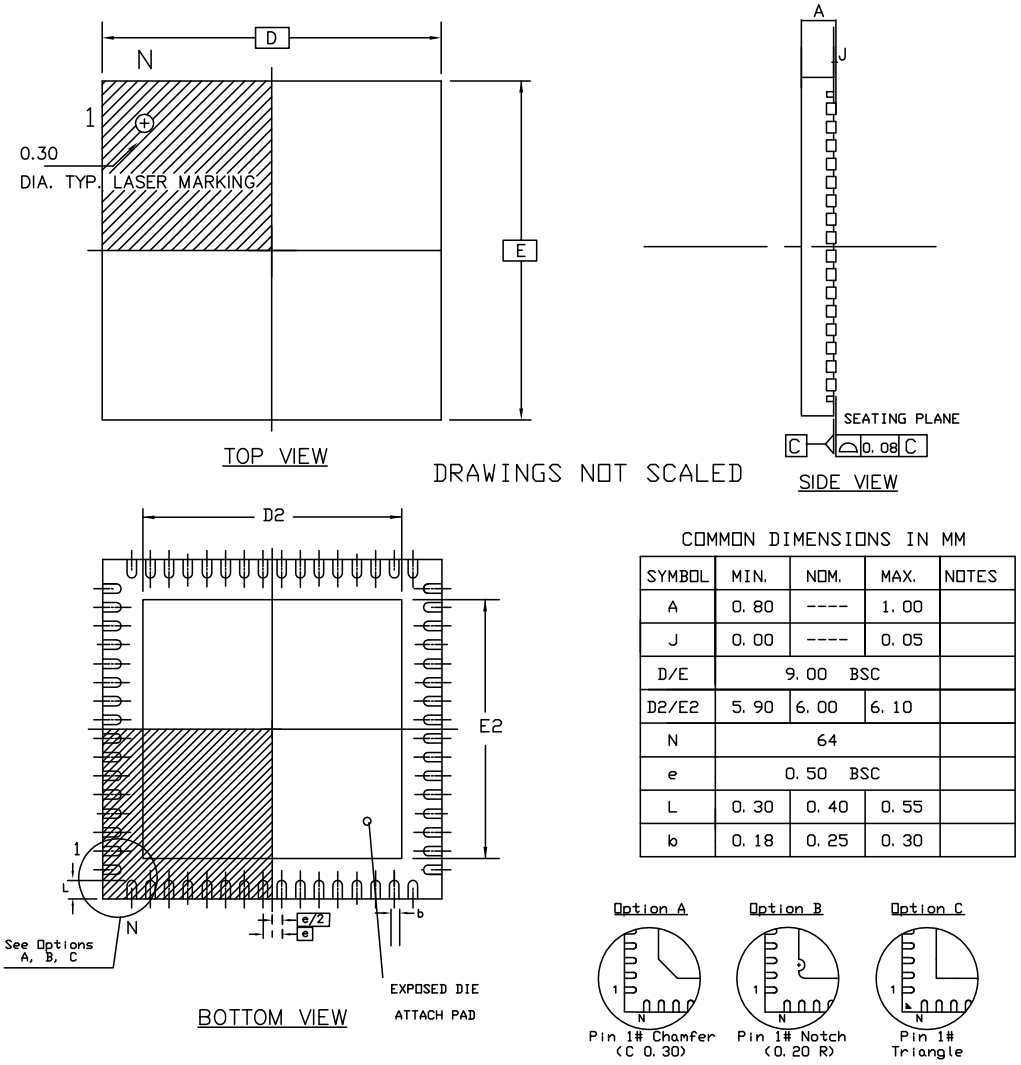
Note: 1. These values are based on simulation and characterization of other AVR microcontrollers manufactured in the same process technology. These values are not covered by test limits in production.

Figure 7-21. Ethernet MAC RMII Mode



8.2 Package Drawings

Figure 8-1. QFN-64 package drawing



SYMBOL	MIN.	NOM.	MAX.	NOTES
A	0.80	----	1.00	
J	0.00	----	0.05	
D/E		9.00 BSC		
D2/E2	5.90	6.00	6.10	
N		64		
e		0.50 BSC		
L	0.30	0.40	0.55	
b	0.18	0.25	0.30	

Note: The exposed pad is not connected to anything internally, but should be soldered to ground to increase board level reliability.

Table 8-2. Device and Package Maximum Weight

200	mg

Table 8-3. Package Characteristics

Moisture Sensitivity Level	Jdec J-STD0-20D - MSL 3

Table 8-4. Package Reference

JEDEC Drawing Reference	MS-026
JESD97 Classification	E3

Fix/Workaround
None.

3 **In host mode, the disconnection during OUT transition is not supported**
In USB host mode, a pipe can not work if the previous USB device disconnection has occurred during a USB transfer.
Fix/Workaround
Reset the USBC (USBCON.USB=0 and =1) after a device disconnection (UHINT.DDISCI).

4 **In USB host mode, entering suspend mode can fail**
In USB host mode, entering suspend mode can fail when UHCON.SOFE=0 is done just after a SOF reception (UHINT.HSOFI).
Fix/Workaround
Check that UHNUM.FLENHIGH is below 185 in Full speed and below 21 in Low speed before clearing UHCON.SOFE.

5 **In USB host mode, entering suspend mode for low speed device can fail when the USB freeze (USBCON.FRZCLK=1) is done just after UHCON.SOFE=0.**
Fix/Workaround
When entering suspend mode (UHCON.SOFE is cleared), check that USBFSM.DRDSTATE is not equal to three before freezing the clock (USBCON.FRZCLK=1).

10.1.11 WDT

1 **WDT Control Register does not have synchronization feedback**
When writing to the Timeout Prescale Select (PSEL), Time Ban Prescale Select (TBAN), Enable (EN), or WDT Mode (MODE) fieldss of the WDT Control Register (CTRL), a synchronizer is started to propagate the values to the WDT clcok domain. This synchronization takes a finite amount of time, but only the status of the synchronization of the EN bit is reflected back to the user. Writing to the synchronized fields during synchronization can lead to undefined behavior.
Fix/Workaround
-When writing to the affected fields, the user must ensure a wait corresponding to 2 clock cycles of both the WDT peripheral bus clock and the selected WDT clock source.
-When doing writes that changes the EN bit, the EN bit can be read back until it reflects the written value.

10.2 rev D

10.2.1 ADCIFA

1. **ADCREFP/ADCREFN can not be selected as an external ADC reference by setting the ADCIFA.CFG.EXREF bit to one**
   Fix/Workaround
   A voltage reference can be applied on ADCREFP/ADCREFN pins if the ADCIFA.CFG.EXREF bit is set to zero, the ADCIFA.CFG.RS bit is set to zero and the voltage reference applied on ADCREFP/ADCREFN pins is higher than the internal 1V reference.

10.2.2 AST

1. **AST wake signal is released one AST clock cycle after the BUSY bit is cleared**
   After writing to the Status Clear Register (SCR) the wake signal is released one AST clock cycle after the BUSY bit in the Status Register (SR.BUSY) is cleared. If entering sleep mode directly after the BUSY bit is cleared the part will wake up immediately.
   Fix/Workaround
   Read the Wake Enable Register (WER) and write this value back to the same register. Wait for BUSY to clear before entering sleep mode.

10.2.3 aWire

1. **aWire MEMORY_SPEED_REQUEST command does not return correct CV**
   The aWire MEMORY_SPEED_REQUEST command does not return a CV corresponding to the formula in the aWire Debug Interface chapter.
   Fix/Workaround
   Issue a dummy read to address 0x100000000 before issuing the MEMORY_SPEED_REQUEST command and use this formula instead:

$$f_{sab} = \frac{7 f_{aw}}{CV - 3}$$

10.2.4 GPIO

1. **Clearing Interrupt flags can mask other interrupts**
   When clearing interrupt flags in a GPIO port, interrupts on other pins of that port, happening in the same clock cycle will not be registered.
   Fix/Workaround
   Read the PVR register of the port before and after clearing the interrupt to see if any pin change has happened while clearing the interrupt. If any change occurred in the PVR between the reads, they must be treated as an interrupt.

10.2.5 Power Manager

1. **Clock Failure Detector (CFD) can be issued while turning off the CFD**
   While turning off the CFD, the CFD bit in the Status Register (SR) can be set. This will change the main clock source to RCSYS.
   Fix/Workaround
   Solution 1: Enable CFD interrupt. If CFD interrupt is issues after turning off the CFD, switch back to original main clock source.
   Solution 2: Only turn off the CFD while running the main clock on RCSYS.

2 **Requesting clocks in idle sleep modes will mask all other PB clocks than the requested**
In idle or frozen sleep mode, all the PB clocks will be frozen if the TWIS or the AST need to wake the cpu up.
Fix/Workaround
Disable the TWIS or the AST before entering idle or frozen sleep mode.

3 **TWIS may not wake the device from sleep mode**
If the CPU is put to a sleep mode (except Idle and Frozen) directly after a TWI Start condition, the CPU may not wake upon a TWIS address match. The request is NACKed.
Fix/Workaround
When using the TWI address match to wake the device from sleep, do not switch to sleep modes deeper than Frozen. Another solution is to enable asynchronous EIC wake on the TWIS clock (TWCK) or TWIS data (TWD) pins, in order to wake the system up on bus events.

10.2.6 SCIF

1 **PLLCOUNT value larger than zero can cause PLLEN glitch**
Initializing the PLLCOUNT with a value greater than zero creates a glitch on the PLLEN signal during asynchronous wake up.
Fix/Workaround
The lock-masking mechanism for the PLL should not be used.
The PLLCOUNT field of the PLL Control Register should always be written to zero.

2 **PLL lock might not clear after disable**
Under certain circumstances, the lock signal from the Phase Locked Loop (PLL) oscillator may not go back to zero after the PLL oscillator has been disabled. This can cause the propagation of clock signals with the wrong frequency to parts of the system that use the PLL clock.
Fix/Workaround
PLL must be turned off before entering STOP, DEEPSTOP or STATIC sleep modes. If PLL has been turned off, a delay of 30us must be observed after the PLL has been enabled again before the SCIF.PLL0LOCK bit can be used as a valid indication that the PLL is locked.

3 **BOD33 reset locks the device**
If BOD33 is enabled as a reset source (SCIF.BOD33.CTRL=0x1) and when VDDIN_33 power supply voltage falls below the BOD33 voltage (SCIF.BOD33.LEVEL), the device is locked permanently under reset even if the power supply goes back above BOD33 reset level. In order to unlock the device, an external reset event should be applied on RESET_N.
Fix/Workaround
Use an external BOD on VDDIN_33 or an external reset source.

10.2.7 SPI

1 **SPI data transfer hangs with CSR0.CSAAT==1 and MR.MODFDIS==0**
When CSR0.CSAAT==1 and mode fault detection is enabled (MR.MODFDIS==0), the SPI module will not start a data transfer.
Fix/Workaround
Disable mode fault detection by writing a one to MR.MODFDIS.

2 **Disabling SPI has no effect on the SR.TDRE bit**
Disabling SPI has no effect on the SR.TDRE bit whereas the write data command is filtered when SPI is disabled. Writing to TDR when SPI is disabled will not clear SR.TDRE. If SPI is disabled during a PDCA transfer, the PDCA will continue to write data to TDR until its buffer is empty, and this data will be lost.
Fix/Workaround
Disable the PDCA, add two NOPs, and disable the SPI. To continue the transfer, enable the SPI and PDCA.

3 **SPI disable does not work in SLAVE mode**
SPI disable does not work in SLAVE mode.
Fix/Workaround
Read the last received data, then perform a software reset by writing a one to the Software Reset bit in the Control Register (CR.SWRST).

4 **SPI bad serial clock generation on 2nd chip_select when SCBR=1, CPOL=1, and NCPHA=0**
When multiple chip selects (CS) are in use, if one of the baudrates equal 1 while one (CSRn.SCBR=1) of the others do not equal 1, and CSRn.CPOL=1 and CSRn.NCPHA=0, then an additional pulse will be generated on SCK.
Fix/Workaround
When multiple CS are in use, if one of the baudrates equals 1, the others must also equal 1 if CSRn.CPOL=1 and CSRn.NCPHA=0.

10.2.8 TC

1 **Channel chaining skips first pulse for upper channel**
When chaining two channels using the Block Mode Register, the first pulse of the clock between the channels is skipped.
Fix/Workaround
Configure the lower channel with RA = 0x1 and RC = 0x2 to produce a dummy clock cycle for the upper channel. After the dummy cycle has been generated, indicated by the SR.CPCS bit, reconfigure the RA and RC registers for the lower channel with the real values.

10.2.9 TWIM

1 **SMBALERT bit may be set after reset**
For TWIM0 and TWIM1 modules, the SMBus Alert (SMBALERT) bit in the Status Register (SR) might be erroneously set after system reset.
Fix/Workaround
After system reset, clear the SR.SMBALERT bit before commencing any TWI transfer.

For TWIM2 module, the SMBus Alert (SMBALERT) is not implemented but the bit in the Status Register (SR) is erroneously set once TWIM2 is enabled.
Fix/Workaround
None.

2 **TWIM TWALM polarity is wrong**
The TWALM signal in the TWIM is active high instead of active low.
Fix/Workaround
Use an external inverter to invert the signal going into the TWIM. When using both TWIM and TWIS on the same pins, the TWALM cannot be used.

10.2.10 TWIS

1. **Clearing the NAK bit before the BTF bit is set locks up the TWI bus**
When the TWIS is in transmit mode, clearing the NAK Received (NAK) bit of the Status Register (SR) before the end of the Acknowledge/Not Acknowledge cycle will cause the TWIS to attempt to continue transmitting data, thus locking up the bus.
Fix/Workaround
Clear SR.NAK only after the Byte Transfer Finished (BTF) bit of the same register has been set.

2. **TWIS stretch on Address match error**
When the TWIS stretches TWCK due to a slave address match, it also holds TWD low for the same duration if it is to be receiving data. When TWIS releases TWCK, it releases TWD at the same time. This can cause a TWI timing violation.
Fix/Workaround
None.

3. **TWALM forced to GND**
The TWALM pin is forced to GND when the alternate function is selected and the TWIS module is enabled.
Fix/Workaround
None.

10.2.11 USBC

1. **UPINRQx.INRQ field is limited to 8-bits**
In Host mode, when using the UPINRQx.INRQ feature together with the multi-packet mode to launch a finite number of packet among multi-packet, the multi-packet size (located in the descriptor table) is limited to the UPINRQx.INRQ value multiply by the pipe size.
Fix/Workaround
UPINRQx.INRQ value shall be less than the number of configured multi-packet.

2. **In USB host mode, downstream resume feature does not work (UHCON.RESUME=1).**
Fix/Workaround
None.

3. **In host mode, the disconnection during OUT transition is not supported**
In USB host mode, a pipe can not work if the previous USB device disconnection has occurred during a USB transfer.
Fix/Workaround
Reset the USBC (USBCON.USB=0 and =1) after a device disconnection (UHINT.DDISCI).

4. **In USB host mode, entering suspend mode can fail**
In USB host mode, entering suspend mode can fail when UHCON.SOFE=0 is done just after a SOF reception (UHINT.HSOFI).
Fix/Workaround
Check that UHNUM.FLENHIGH is below 185 in Full speed and below 21 in Low speed before clearing UHCON.SOFE.

5. **In USB host mode, entering suspend mode for low speed device can fail when the USB freeze (USBCON.FRZCLK=1) is done just after UHCON.SOFE=0.**
Fix/Workaround
When entering suspend mode (UHCON.SOFE is cleared), check that USBFSM.DRDSTATE is not equal to three before freezing the clock (USBCON.FRZCLK=1).